



Features

- High thermal conductivity, low coefficient of expansion
- Ultra-flat capabilities
- High stiffness, better wear resistance
- Lightweight design
- High purity, no metal ion pollution
- Customized requirements accepted

Description

This chuck adopts lightweight design, and is made of materials with low coefficients of thermal expansion: pressureless sintered silicon carbide, silicon carbide, silicon nitride and aluminum nitride.

This chuck features high stiffness, high thermal conductivity, low thermal expansion, high stability, high purity, uniform grain size, etc., which effectively reduces contamination from Particle and chemical cleaning and extends service lifetime.

Applications

- Semiconductor Inspection Equipment
- Bonding Equipment
- Wafer Manufacturing

Technical Specifications

	Data	Unit
Flatness	0.5	μm
Applicable specifications	6/8' 12' 8/12'	
Surface feature	pin type, ring type	
Pin height	0.05-0.2	mm
Pin min. diameter	φ0.2	mm
Min. spacing	3	mm
Min. seal width	0.7	mm
Surface roughness	Ra 0.02	μm
Thickness tolerance	±0.01	mm
Diameter tolerance	±0.01	mm
Parallelism tolerance	≤3	μm